| L | Hits | Search Text | DB | Time stamp |
|--------|------|---|-----------|------------|
| Number | | | | |
| 1 | 147 | | USPAT; | 2004/03/16 |
| | | same ((thin thinfilm (thin adj film)) | US-PGPUB; | 19:40 |
| | | same ((taper tapered) same ((silicon | EPO; JPO; | |
| | | silicon semiconductor bulk gaas) with | DERWENT; | |
| | | (substrate carrier)))) | IBM_TDB | |
| 2 | 203 | ' | USPAT; | 2004/03/16 |
| | | same ((thin thinfilm (thin adj film)) | US-PGPUB; | 19:41 |
| | | same ((taper tapered) same ((silicon | EPO; JPO; | |
| | | silicon semiconductor bulk gaas) with | DERWENT; | |
| | | (substrate carrier)))) | IBM_TDB | |
| 3 | 56 | , , , | USPAT; | 2004/03/16 |
| | | same ((thin thinfilm (thin adj film)) | US-PGPUB; | 19:41 |
| | | same ((taper tapered) same ((silicon | EPO; JPO; | |
| | | silicon semiconductor bulk gaas) with | DERWENT; | |
| | | (substrate carrier))))) not ((thourgh | IBM_TDB | |
| | | hole thoughhole opening gap) same ((thin | | |
| | | thinfilm (thin adj film)) same ((taper | İ | |
| | | tapered) same ((silicon silicon | | |
| | | semiconductor bulk gaas) with (substrate | | |
| | | carrier))))) | | <u> </u> |

| L | Hits | Search Text | DB | Time stamp |
|--------|--------|---|-----------|------------|
| Number | | | | |
| 1 | 517583 | (silicon silicon semiconductor bulk gaas) | USPAT; | 2004/03/16 |
| | | with (substrate carruer) | US-PGPUB; | 10:28 |
| | | | EPO; JPO; | |
| | | | DERWENT; | |
| | | | IBM TDB | |
| 2 | 3958 | (taper tapered) same ((silicon silicon | USPAT; | 2004/03/16 |
| - | | semiconductor bulk gaas) with (substrate | US-PGPUB; | 10:28 |
| } | | carruer)) | EPO; JPO; | 10.20 |
| | | Carracti | DERWENT; | |
| | | | IBM TDB | 1 |
| | 100 | (+1-1 +1-1 5:1 (+1-11 5:1) | | 2004/02/16 |
| 3 | 496 | (thin thinfilm (thin adj film)) same | USPAT; | 2004/03/16 |
| | | ((taper tapered) same ((silicon silicon | US-PGPUB; | 10:29 |
| | | semiconductor bulk gaas) with (substrate | EPO; JPO; | |
| | | carruer))) | DERWENT; | ĺ |
| | | | IBM_TDB | |
| 4 | 145 | (thourgh hole thoughhole opening gap) | USPAT; | 2004/03/16 |
| | | same ((thin thinfilm (thin adj film)) | US-PGPUB; | 10:30 |
| | | same ((taper tapered) same ((silicon | EPO; JPO; | |
| | | silicon semiconductor bulk gaas) with | DERWENT; | |
| | | (substrate carruer)))) | IBM TDB | |